

2A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

- · Glass Passivated Chip Junction
- Reverse Voltage 2000 V
- Forward Current 2 A
- · High Surge Current Capability
- Designed for Surface Mount Application

MECHANICAL DATA

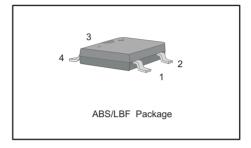
· Case: ABS/LBF

• Terminals: Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 88mg/0.0031oz

PINNING

PIN	DESCRIPTION				
1	Input Pin (~)				
2	Input Pin (~)				
3	Output Anode (+)				
4	Output Cathode (-)				



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	TB22000S	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	2000	V
Maximum RMS voltage	V _{RMS}	1400	V
Maximum DC Blocking Voltage	V _{DC}	2000	V
Average Rectified Output Current at T _L = 88 °C	Io	2.0	А
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	40	А
I ² t Rating for Fusing(T < 8.3ms)	I ² t	6.7	A ² S
Forward Voltage per element @I _F =1.0A @I _F =2.0A	V _F	1.05 1.3	V
Maximum DC Reverse Current @T _A =25 °C at Rated DC Blocking Voltage @T _A =125 °C	I _R	5.0 100	μA
Typical Junction Capacitance (Note1)	C _j	12	pF
Typical Thermal Resistance (Note2)	$egin{array}{c} R_{ heta JA} \ R_{ heta JL} \ R_{ heta JC} \end{array}$	40 20 10	°C/W
Operating and Storage Temperature Range	Tj, Tstg	-55 ~ +150	°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with $4 \times 1.5" \times 1.5"$ (3.81×3.81 cm) copper pad.

RATING AND CHARACTERISTICS CURVES (TB22000S)

Fig.1 Average Rectified Output Current Derating Curve

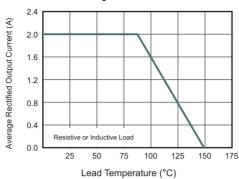


Fig.2 Typical Reverse Characteristics

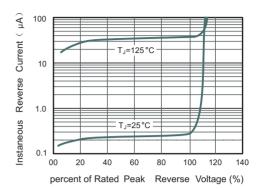


Fig.3 Typical Instaneous Forward Characteristics

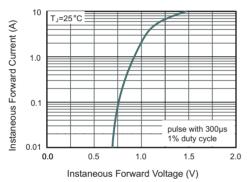


Fig.4 Typical Junction Capacitance

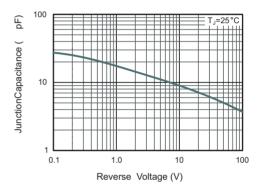
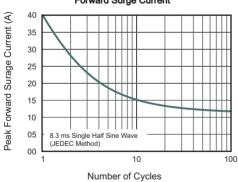


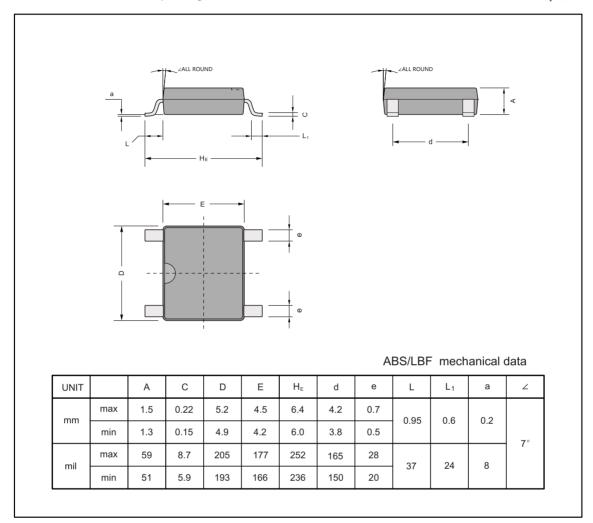
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



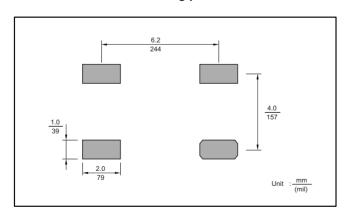
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

ABS/LBF

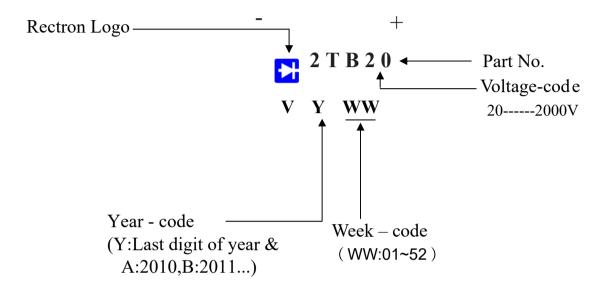


The recommended mounting pad size





Marking Description

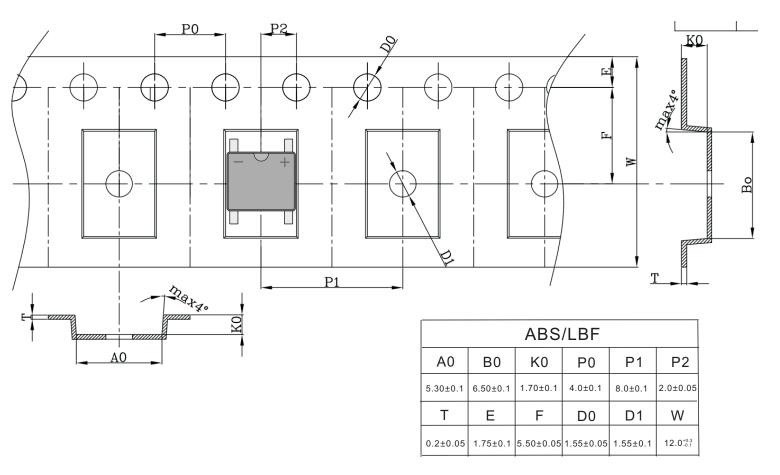


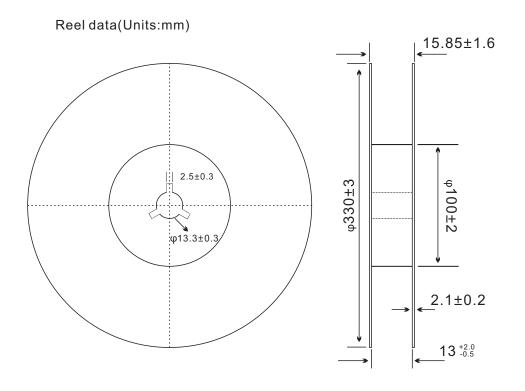
PACKAGE	PACKING CODE	PER REEL (EA)	REEL DIA (mm)	INNER BOX (EA)	BOX SIZE (mm)	CARTON SIZE (mm)	PER CARTON (EA)
ABS/LBF	-T	5,000	330	10,000	336*336*40	345*345*235	50,000



ABS/LBF

Tape data (Units: mm)







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